



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

VSMY2940RG



VSMY2940G



DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2940 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR touch panels

FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: $\lambda_p = 940$ nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: $\phi = \pm 10^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMY2940RG	120	± 10	940	10
VSMY2940G	120	± 10	940	10

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2940RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2940G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100\text{ }\mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	$^{\circ}\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	acc. figure 10, J-STD-020	T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R_{thJA}	250	K/W

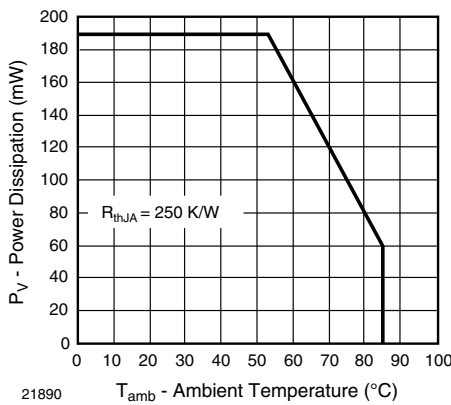


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

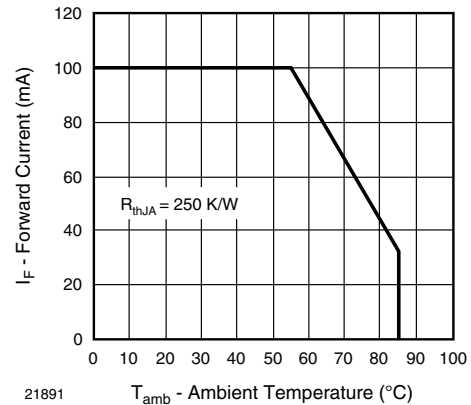


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	V_F		1.55	1.9	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	V_F		2.65		V
Temperature coefficient of V_F	$I_F = 100\text{ mA}$	TK_{V_F}		-2.1		mV/K
Reverse current		I_R	not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0\text{ mW/cm}^2$	C_J		125		pF
Radiant intensity	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	I_e	65	120	195	mW/sr
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	I_e		880		mW/sr
Radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	ϕ_e		55		mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	TK_{ϕ_e}		-0.2		%/K
Angle of half intensity		ϕ		± 10		deg
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	920	940	960	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$		40		nm
Temperature coefficient of λ_p	$I_F = 30\text{ mA}$	TK_{λ_p}		0.25		nm/K
Rise time	$I_F = 100\text{ mA}, 20\% \text{ to } 80\%$	t_r		10		ns
Fall time	$I_F = 100\text{ mA}, 20\% \text{ to } 80\%$	t_f		10		ns



BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

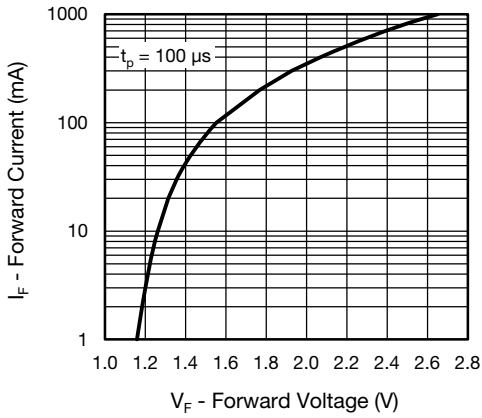


Fig. 3 - Forward Current vs. Forward Voltage

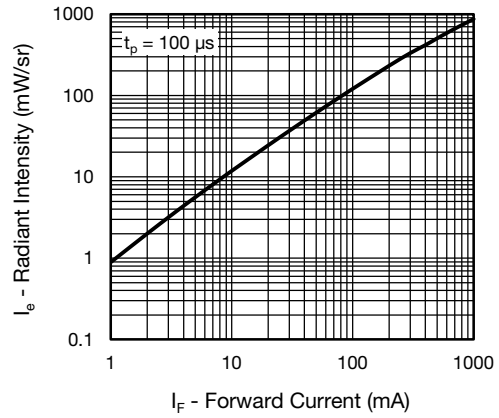


Fig. 6 - Radiant Intensity vs. Forward Current

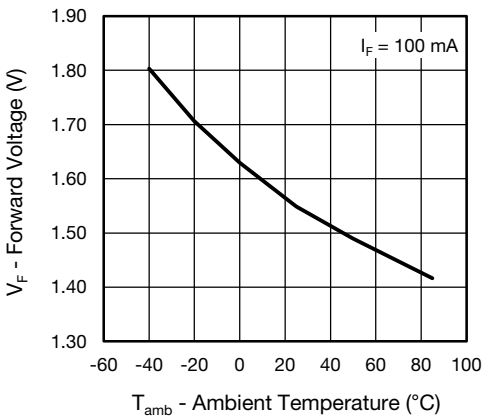


Fig. 4 - Forward Voltage vs. Ambient Temperature

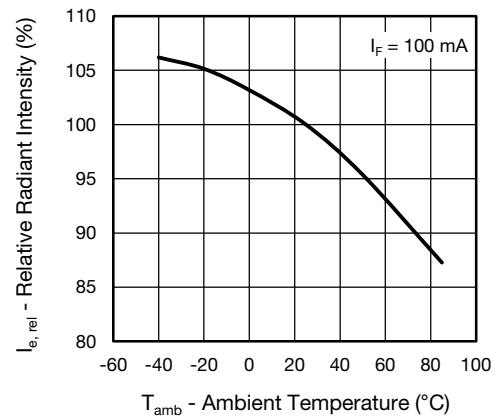


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

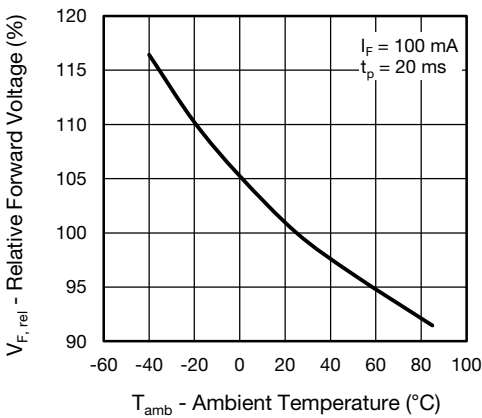


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

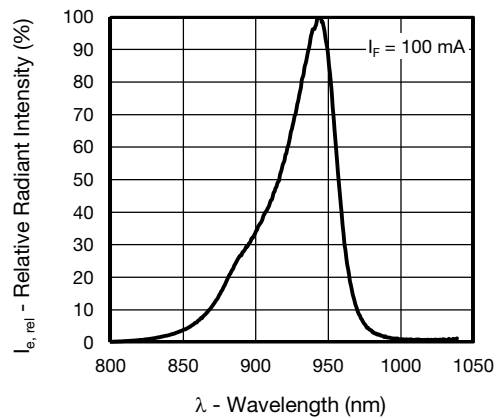


Fig. 8 - Relative Radiant Intensity vs. Wavelength

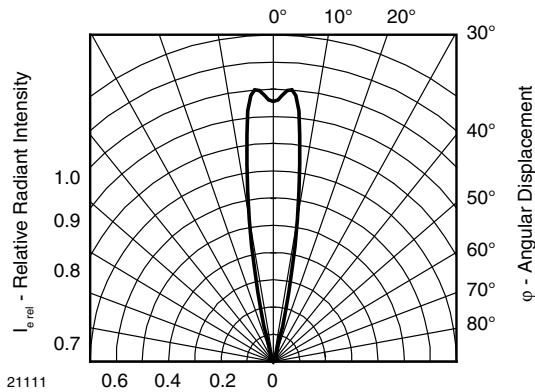


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

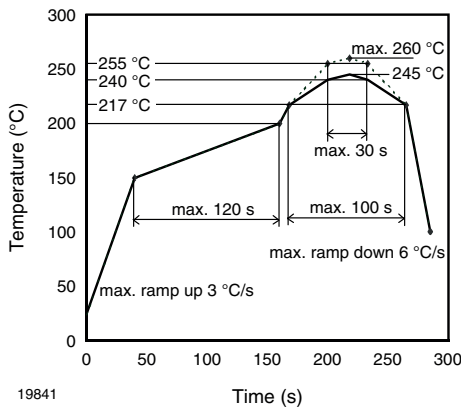


Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, $RH < 60\%$

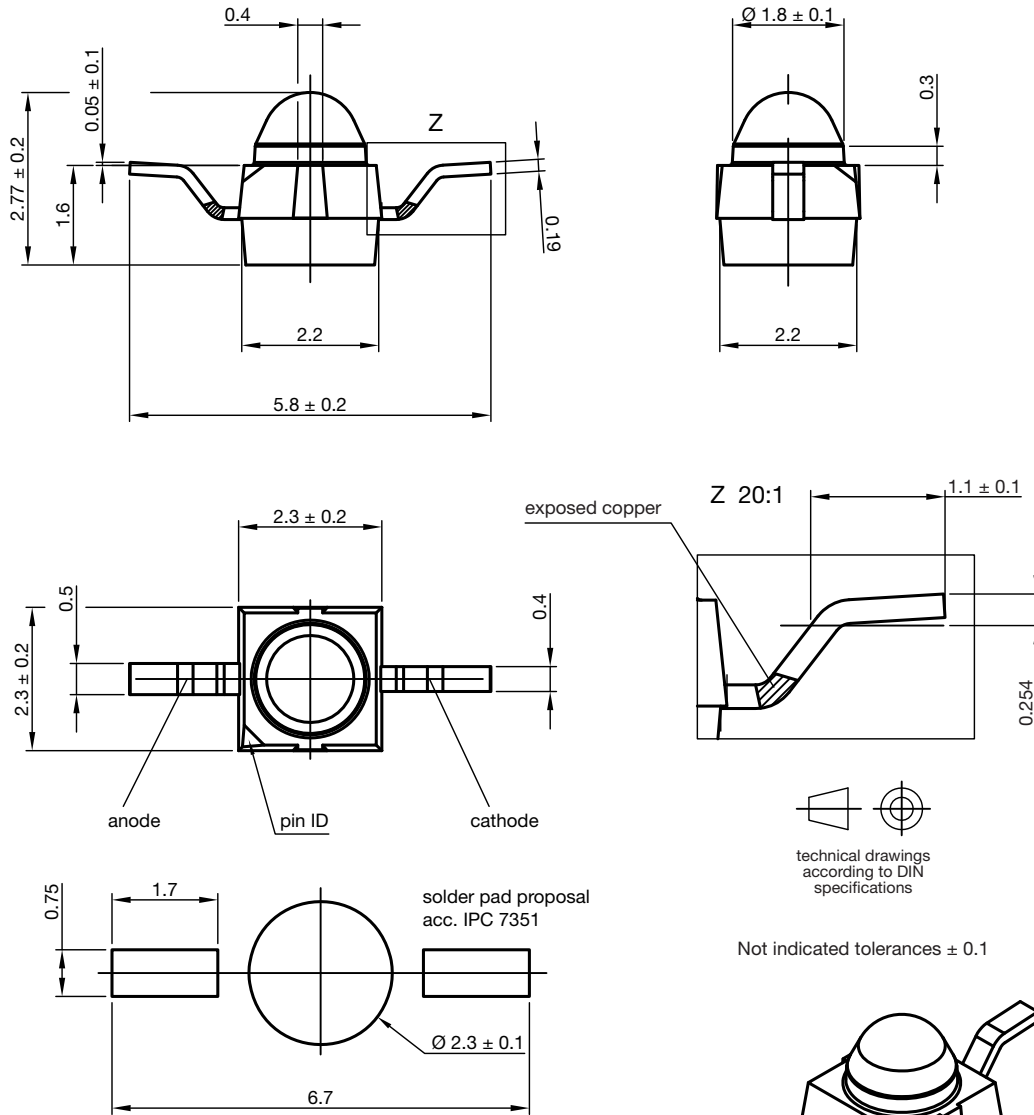
Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

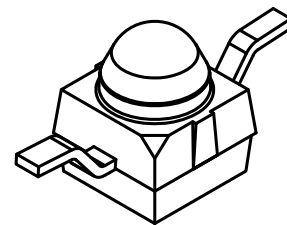
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C} (+ 5\text{ }^{\circ}\text{C})$, $RH < 5\%$.



PACKAGE DIMENSIONS in millimeters: VSMY2940RG

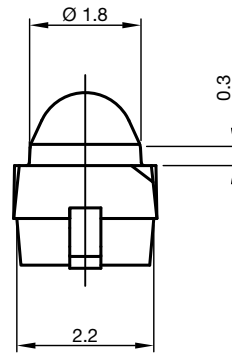
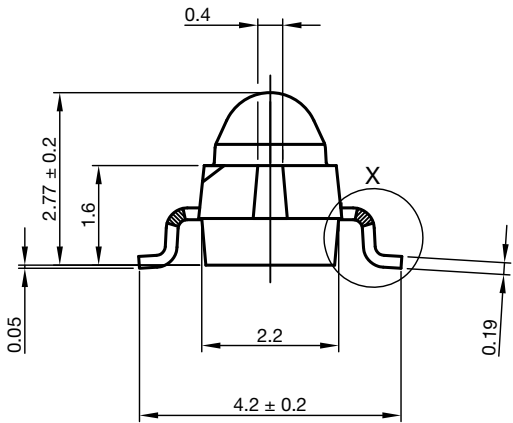


Drawing-No.: 6.544-5391.03-4
Issue: 2; 19.09.14

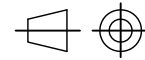
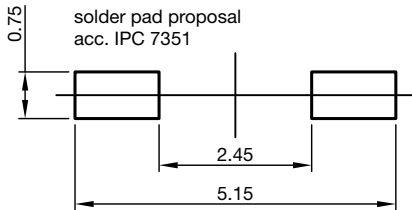
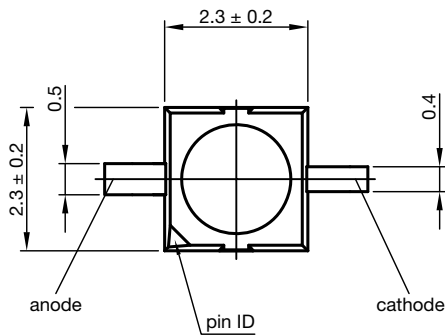
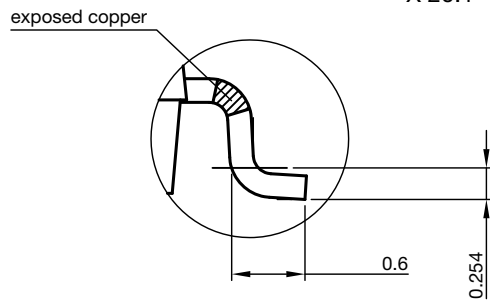




PACKAGE DIMENSIONS in millimeters: VSMY2940G

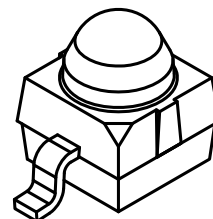


X 20:1



technical drawings according to DIN specifications

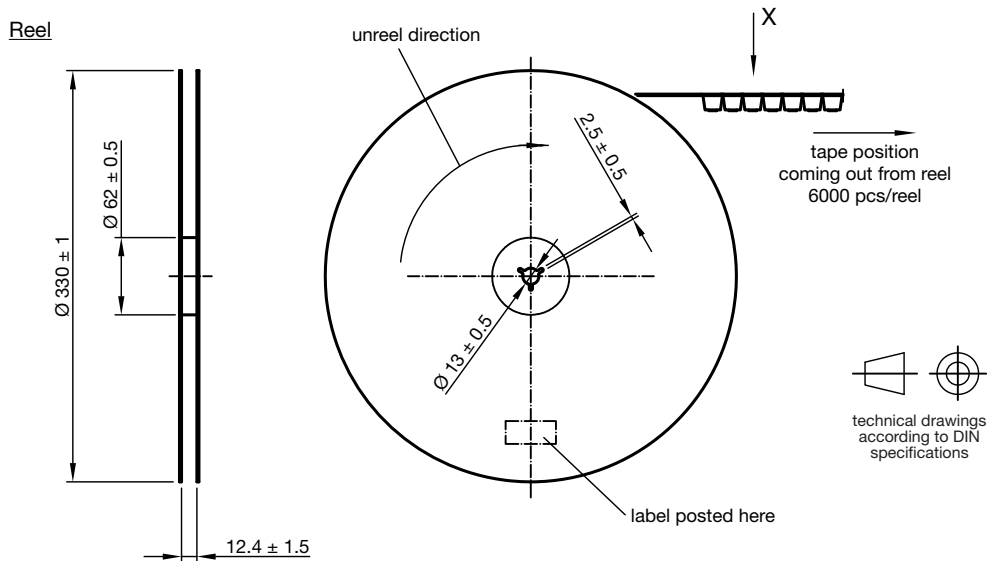
Not indicated tolerances ± 0.1



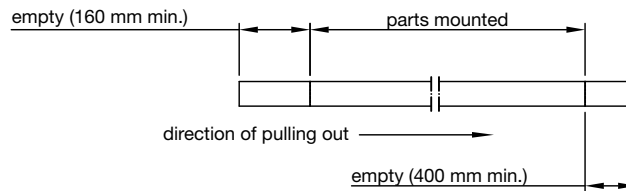
Drawing-No.: 6.544-5383.03-4
Issue: 2; 19.09.14



TAPING AND REEL DIMENSIONS in millimeters: **VSMY2940RG**

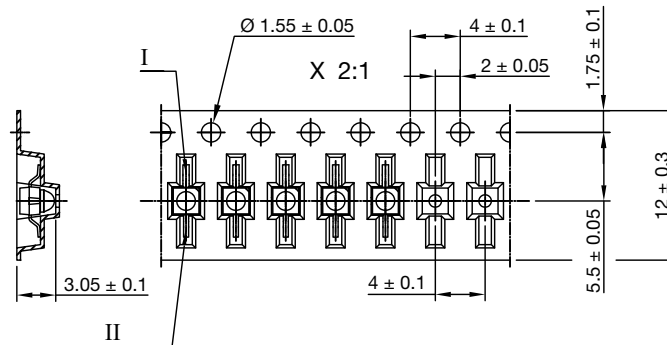


Leader and trailer tape



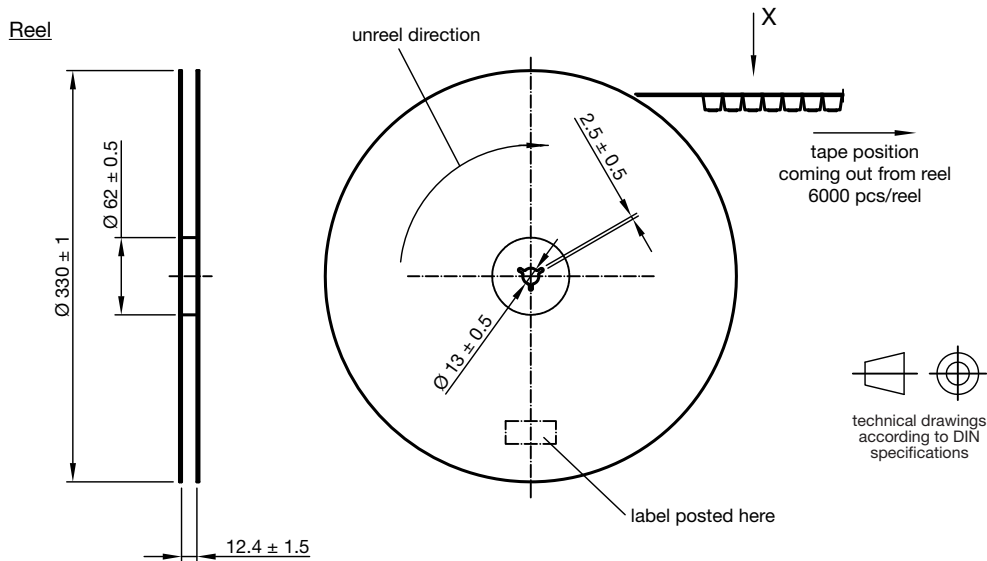
Terminal position in tape

Device	Lead I	Lead II
VENT2000	Collector	Emitter
VENT2500		
VEMD2000		
VEMD2500	Cathode	Anode
VSMB2000		
VSMG2000		
VSMF2890RG	Anode	Cathode
VSMY2850RG		
VSMY2940RG		

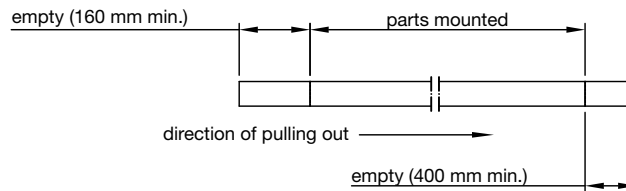


Drawing-No.: 9.800-5100.01-4
Issue: 4; 19.09.14

TAPING AND REEL DIMENSIONS in millimeters: VSMY2940G

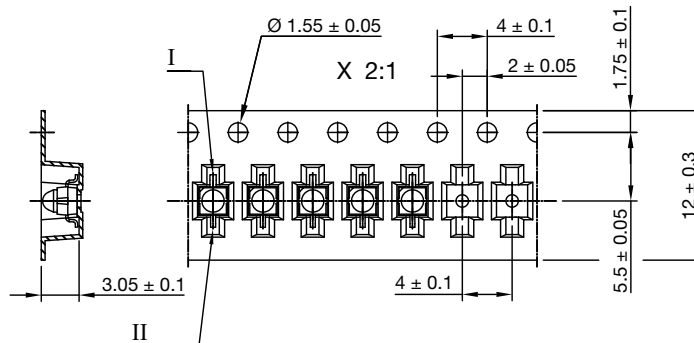


Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II
VSMB2020	Cathode	Anode
VSMG2020		
VEMD2020		
VEMD2520		
VSMF2890G	Collector	Emitter
VEMT2020		
VEMT2520		
VSMY2850G	Anode	Cathode
VSMY2940G		



Drawing-No.: 9.800-5091.01-4
Issue: 5; 19.09.14



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.